Amendment to the Abstract

Please replace the Abstract at paragraph 0045 beginning at page 25 with the following replacement paragraph submitted on a separate sheet as follows:

photolithographic dual damascene trench patterning process is disclosed—including providing an inter-metal dielectric (IMD) layer including at least one via opening extending through a thickness thereof; and, conformally forming an antireflectance coating (ARC) layer over said the IMD layer such that the ARC layer is formed over sidewalls of the at least one via opening to reduce light reflectance.